

		Conductive Ag Paste		
Parameter	Test/Measure	DN-1705	DN-1715	DN-1718
Viscosity @25deg.C	E-viscometer@5rpm	8,500	8,000	9,100
Thixotropic Index @25deg.C	0.5rpm/5rpm	5.2	5.3	4.84
Open Time (for 1*1 mm2 die size)	Hour	6	8	3
Volume Resistance	Ohm.cm	4.0×10^{-4}	2.4×10^{-5}	3×10^{-5}
Thermal Conductivity	W/mk	2	15	22
Die Shear Strength @25 Deg.C with 2*2 mm Ag BSM Die	On Ag/Cu LF (Mpa)	37	30	42.8 (1x1 for Au)
	On Cu PCB (Mpa)	45	30	
Die Shear Strength @260 Deg.C 2*2 mm Ag BSM Die	On Ag/Cu LF (Mpa)	7	8	4.3 (1x1 for Au)
	On Cu PCB (Mpa)	7	8	
Storage Modulus@25 Deg.C	GPa	8.7	12	10
Tg	dC	73	121	120
CTE	ppm	40/182	49/160	50/160
Product Benefit		1.Low modulus 2.High adhesion on Ag, Au & Cu finish	1.Good TC 2.Good reliability	1.Good TC 2.Good reliability